IXYS

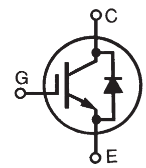
Preliminary Technical Information

GenX3™ 600V IGBT with Diode

IXGH48N60B3D1

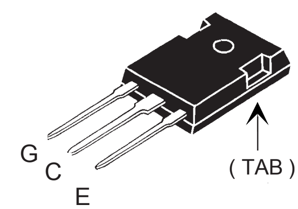
V_{CES} = 600V
I_{C110} = 48A
$V_{CE(sat)}$ ≤ 1.8V

Medium speed low Vsat PT IGBTs 5-40 kHz switching



Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_C = 25°C to 150°C	600	V
V_{CGR}	T_J = 25°C to 150°C, R_{GE} = 1MΩ	600	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C110}	T_C = 110°C	48	A
I_{D110}	T_C = 110°C	30	A
I_{CM}	T_C = 25°C, 1ms	280	A
SSOA (RBSOA)	V_{GE} = 15V, T_{VJ} = 125°C, R_G = 5Ω Clamped inductive load @ ≤ 600V	I_{CM} = 120	A
P_C	T_C = 25°C	300	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	1.6mm (0.062 in.) from case for 10s	300	°C
T_{SOLD}	Plastic body for 10 seconds	260	°C
M_d	Mounting torque	1.13/10	Nm/lb.in.
Weight		6	g

TO-247(IXGH)



G = Gate C = Collector
E = Emitter TAB = Collector

Features

- Optimized for low conduction and switching losses
- Square RBSOA
- Anti-parallel ultra fast diode
- International standard package

Advantages

- High power density
- Low gate drive requirement

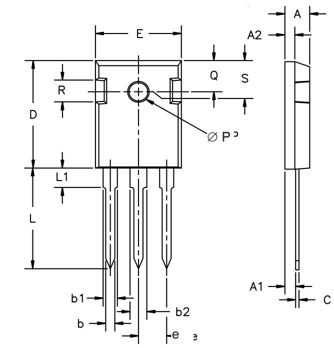
Applications

- Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

Symbol	Test Conditions (T_J = 25°C unless otherwise specified)		Characteristic Values Min.	Typ.	Max.	
BV_{CES}	I_C = 250µA, V_{GE} = 0V		600			V
$V_{GE(th)}$	I_C = 250µA, V_{CE} = V_{GE}		3.0		5.0	V
I_{CES}	V_{CE} = V_{CES} V_{GE} = 0V	 T_J = 125°C			300 1.75	µA mA
I_{GES}	V_{CE} = 0V, V_{GE} = ± 20V				±100	nA
$V_{CE(sat)}$	I_C = 32A, V_{GE} = 15V, Note 1				1.8	V

Symbol	Test Conditions (T_J = 25°C unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	I_C= 30A, V_{CE} = 10V, Note 1	28	46		S
C_{ies}	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz		3980		pF
C_{oes}			190		pF
C_{res}			45		pF
Q_g	I_C = 40A, V_{GE} = 15V, V_{CE} = 0.5 • V_{CES}		115		nC
Q_{ge}			21		nC
Q_{gc}			40		nC
$t_{d(on)}$	**Inductive Load, T_J = 25°C**		22		ns
t_{ri}	I_C = 30A, V_{GE} = 15V		25		ns
E_{on}	V_{CE} = 480V, R_G = 5Ω		0.84		mJ
$t_{d(off)}$			130	200	ns
t_{fi}			116	200	ns
E_{off}			0.66	1.20	mJ
$t_{d(on)}$	**Inductive Load, T_J = 125°C**		19		ns
t_{ri}	I_C = 30A, V_{GE} = 15V		25		ns
E_{on}	V_{CE} = 480V, R_G = 5Ω		1.71		mJ
$t_{d(off)}$			190		ns
t_{fi}			157		ns
E_{off}			1.30		mJ
R_{thJC}				0.42	°C/W
R_{thCS}			0.21		°C/W

TO-247 (IXGH) Outline



Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	4.7	5.3	.185	.209
A_1	2.2	2.54	.087	.102
A_2	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b_1	1.65	2.13	.065	.084
b_2	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L1		4.50		.177
∅P	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15	BSC	242	BSC

Reverse Diode (FRED) (D1 Version ONLY)

Symbol	Test Conditions	Characteristic Values (T_J = 25°C, unless otherwise specified) Min.	Typ.	Max.	
V_F	I_F = 30A, V_{GE} = 0V, Note 1			2.8	V
	T_J = 150°C		1.6		V
I_{RM}	I_F= 30A, V_{GE} = 0V, V_R= 100V -di$_F$/dt =100A/μs		4		A
t_{rr}	I_F = 1A; -di/dt = 100A/μs, V_R = 30V T_J = 100°C		100		ns
R_{thJC}				1.5	°C/W
R_{thCS}			1.5		°C/W

Note 1: Pulse test, t ≤ 300μs; duty cycle, d ≤ 2%.

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

Fig. 1. Output Characteristics @ 25ºC

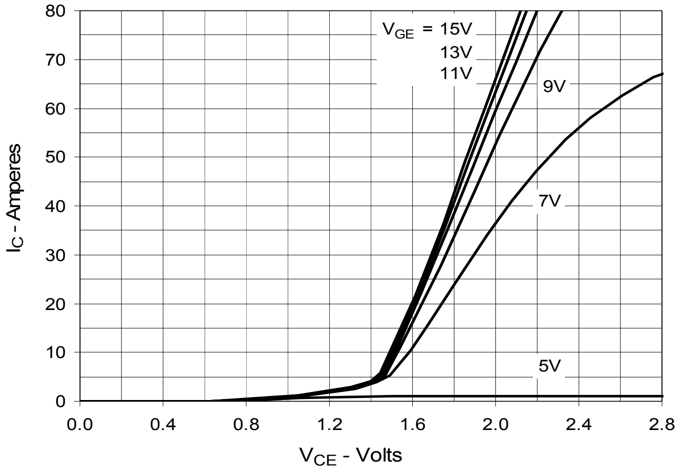


Fig. 2. Extended Output Characteristics @ 25ºC

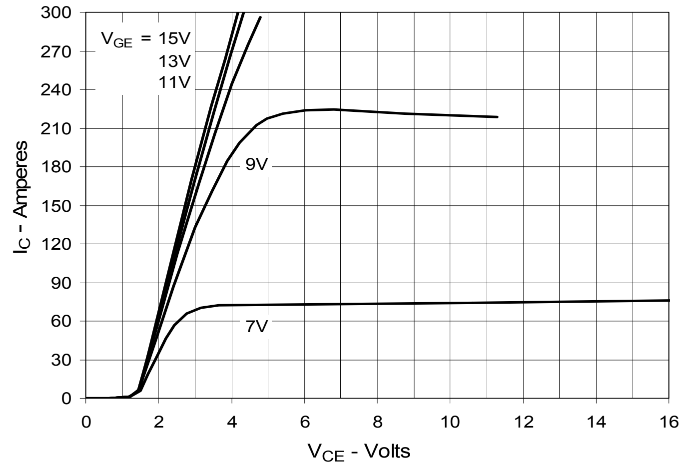


Fig. 3. Output Characteristics @ 125ºC

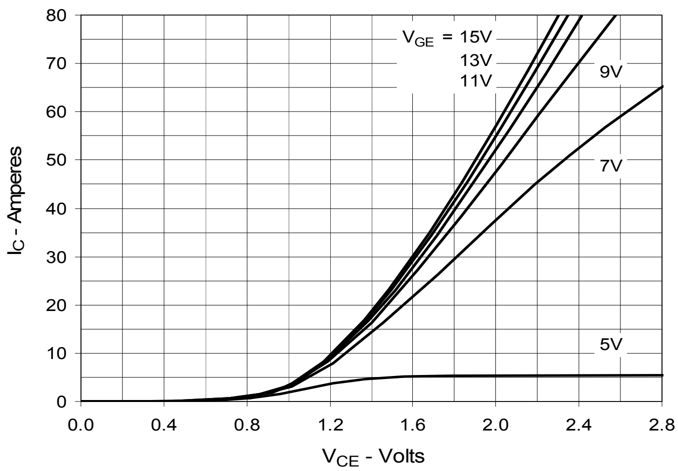


Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

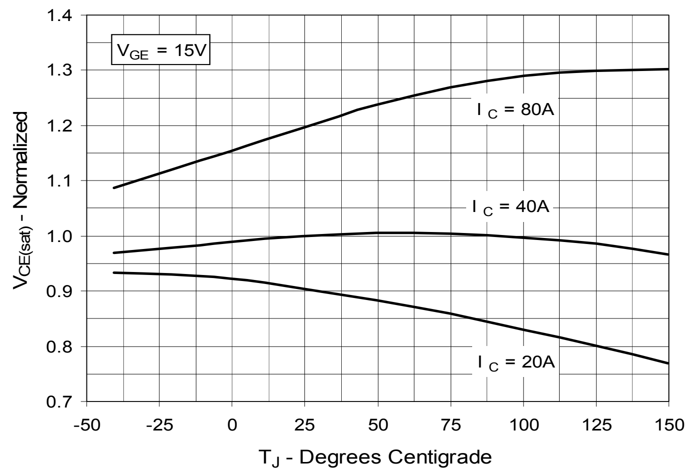


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

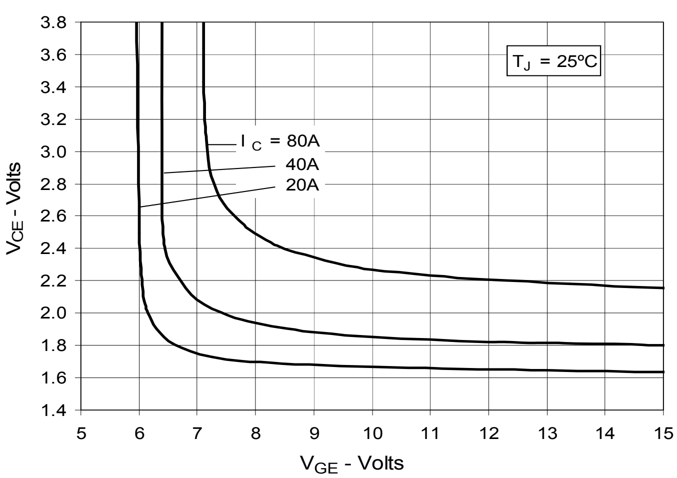


Fig. 6. Input Admittance

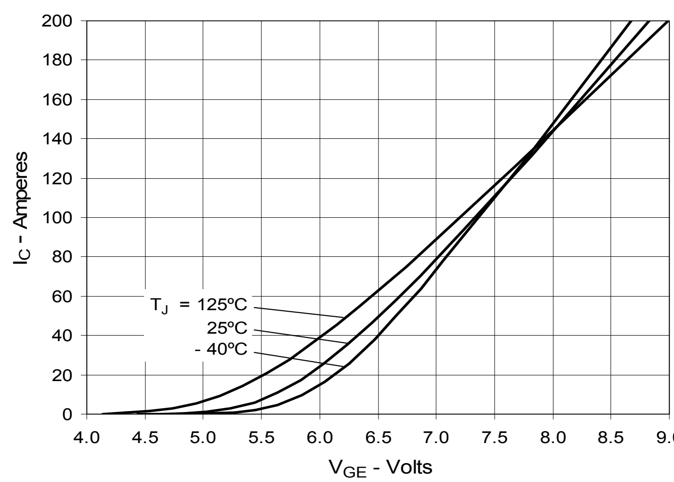


Fig. 7. Transconductance

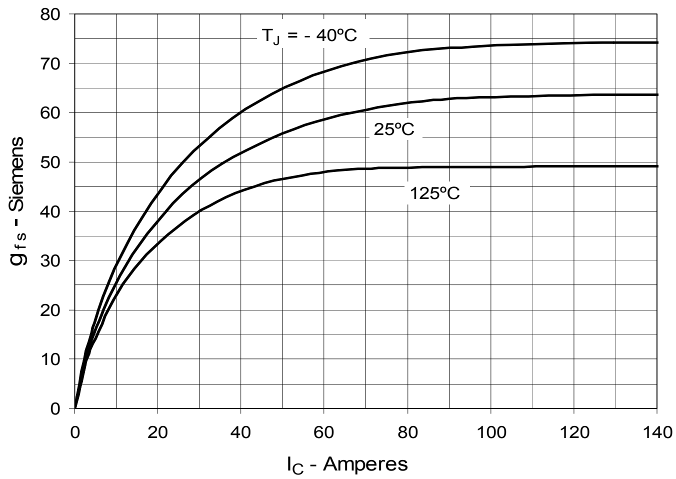


Fig. 8. Gate Charge

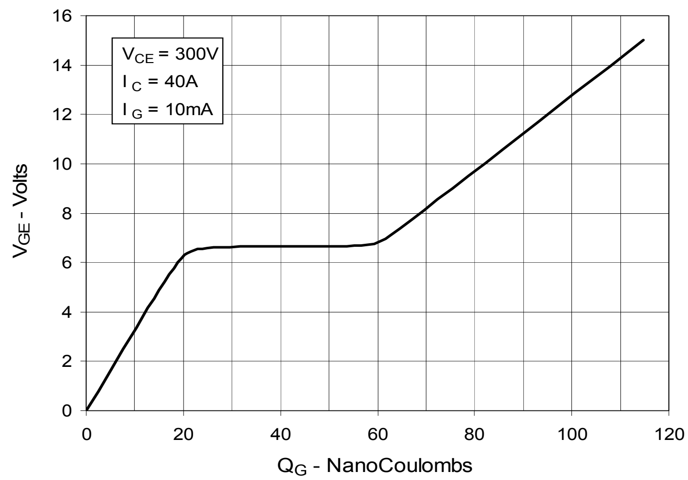


Fig. 9. Capacitance

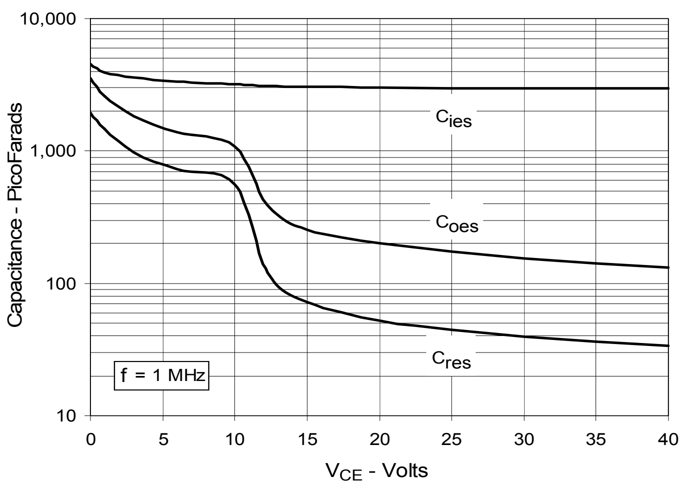


Fig. 10. Reverse-Bias Safe Operating Area

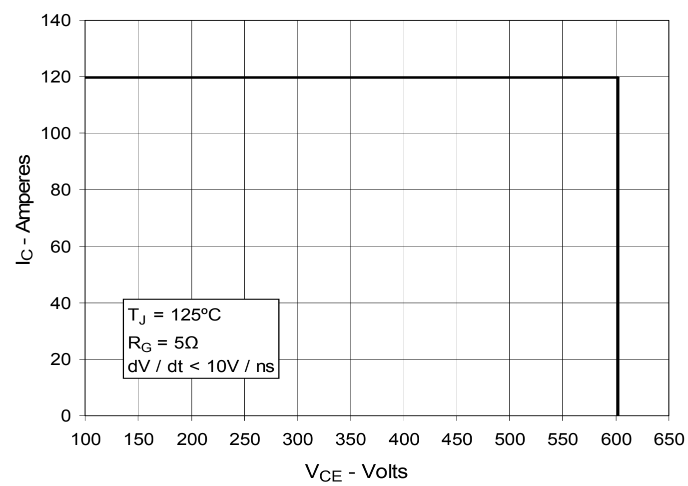
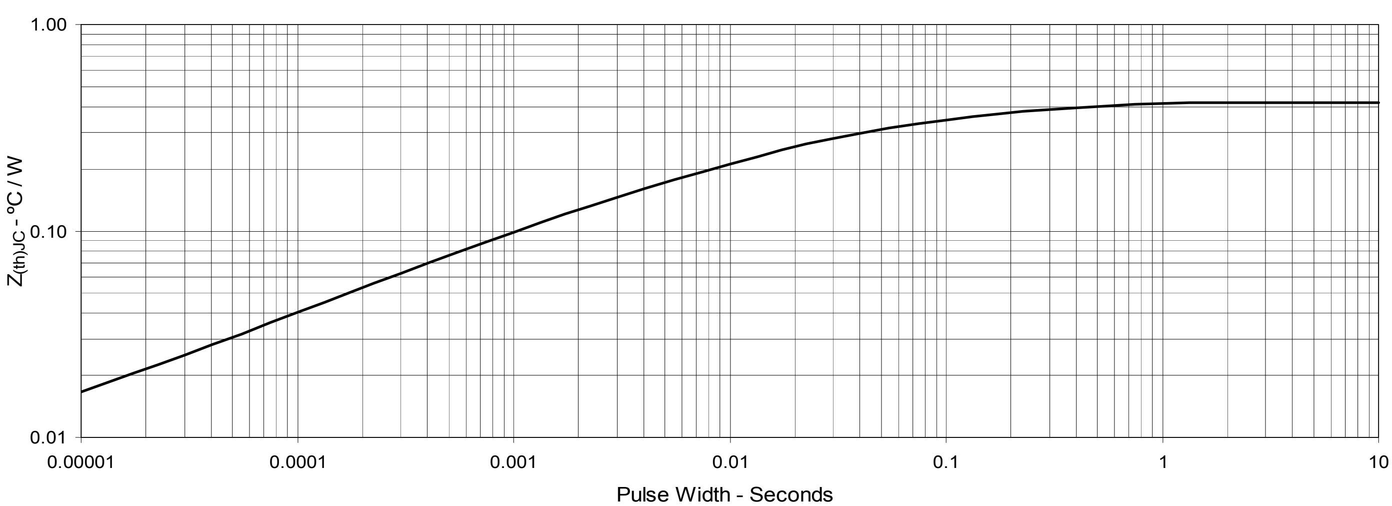


Fig. 11. Maximum Transient Thermal Impedance



IXYS reserves the right to change limits, test conditions and dimensions.

Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance

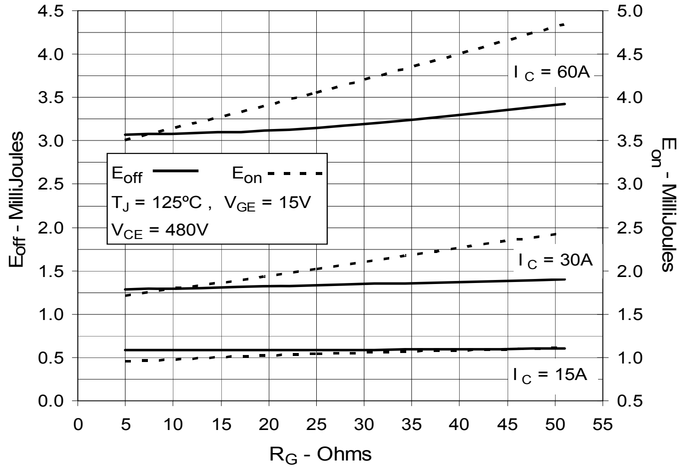


Fig. 13. Inductive Switching Energy Loss vs. Collector Current

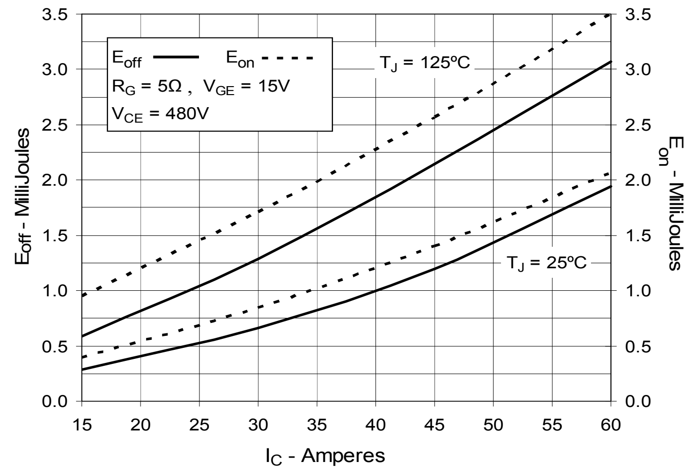


Fig. 14. Inductive Switching Energy Loss vs. Junction Temperature

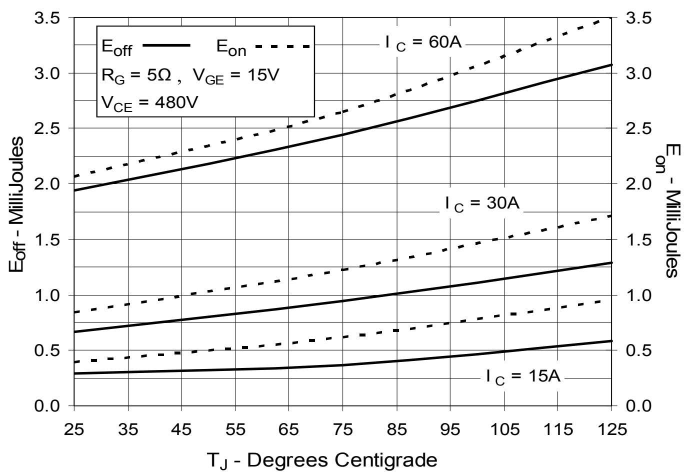


Fig. 15. Inductive Turn-off Switching Times vs. Junction Temperature

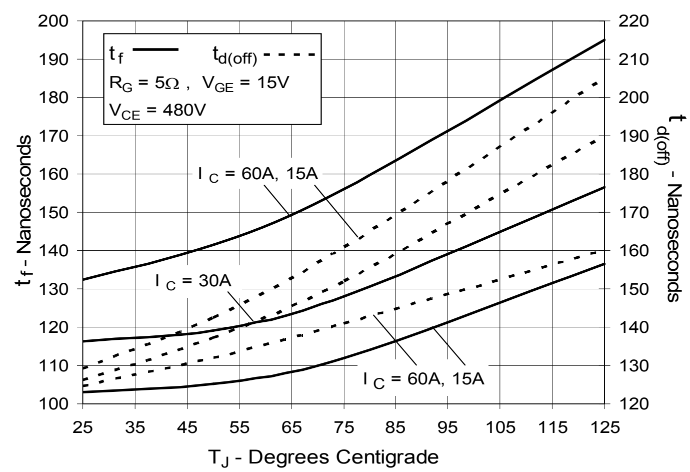


Fig. 16. Inductive Turn-off Switching Times vs. Collector Current

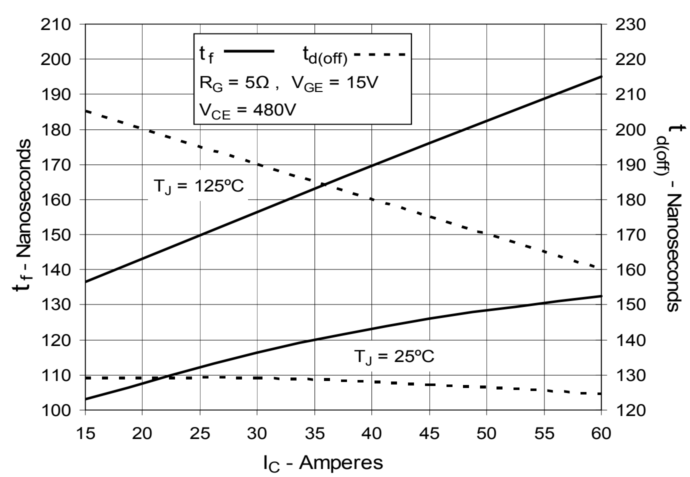


Fig. 17. Inductive Turn-off Switching Times vs. Gate Resistance

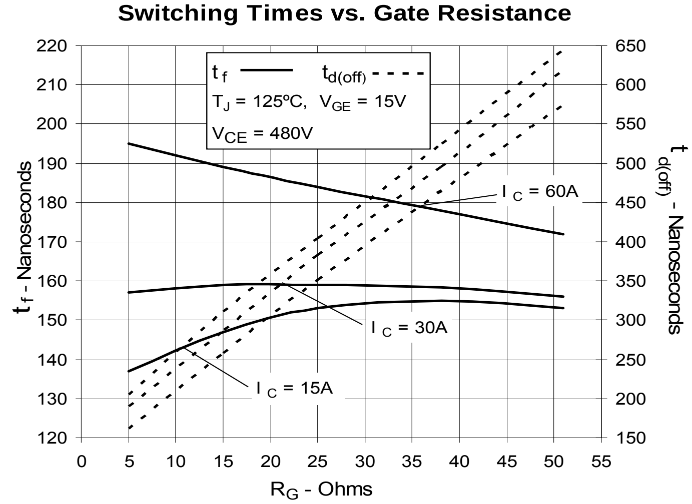


Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance

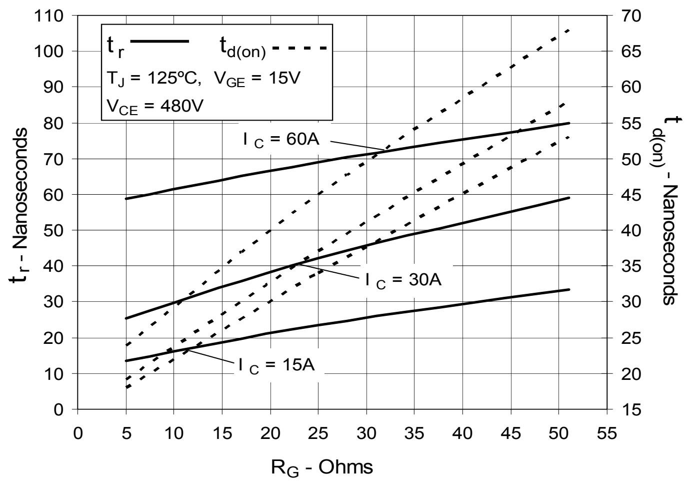


Fig. 19. Inductive Turn-on Switching Times vs. Collector Current

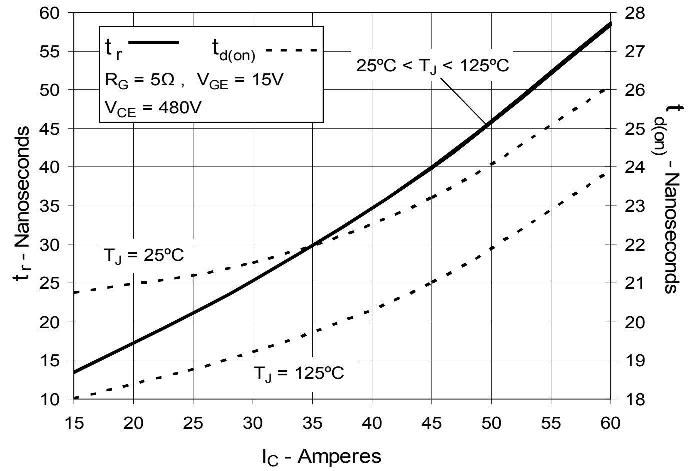


Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature